(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
03 November 2022 (03.11.2022)

WIPO | PCT

(10) International Publication Number
WO 2022/231308 A1

(51) International Patent Classification:
B24B 37/08 (2012.01) *B24D 18/00* (2006.01)
B24B 37/24 (2012.01) *H01L 21/67* (2006.01)
B24D 3/10 (2006.01)

(21) International Application Number:
PCT/KR2022/006034

(22) International Filing Date:
27 April 2022 (27.04.2022)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
63/180,481 27 April 2021 (27.04.2021) US

(71) Applicant: **GLOBALWAFERS CO., LTD.**; No. 8 Industrial East Road 2, Science-Based Industrial Park, Hsinchu (TW).

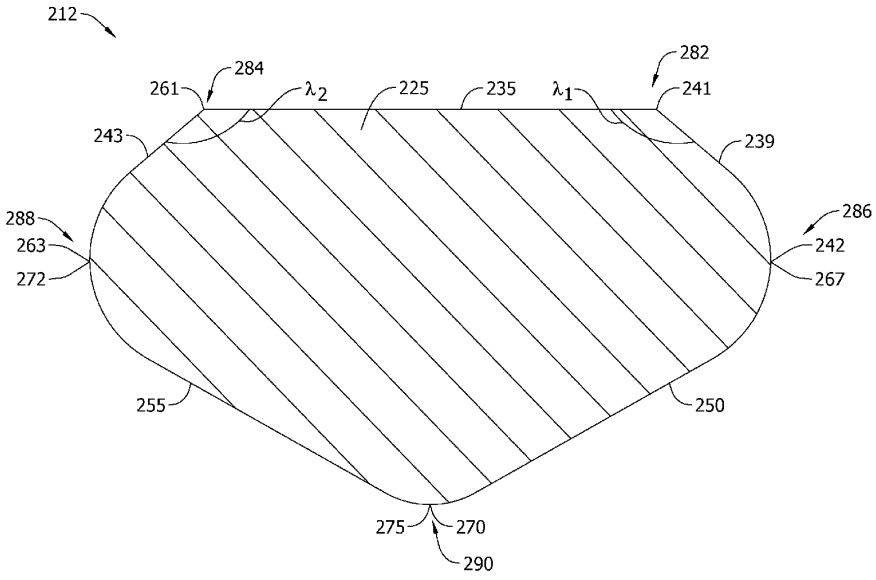
(72) Inventors: **CHOI, Cheulwon**; c/o MEMC Korea Company Ltd., 854, Manghynag-ro, Seonggeo-eup, Seobuk-gu, Cheonan-si, Chungcheongnam-do 31043 (KR). **KIM, Jongsun**; c/o MEMC Korea Company Ltd., 854, Manghynag-ro, Seonggeo-eup, Seobuk-gu, Cheonan-si, Chungcheongnam-do 31043 (KR). **KWEON, Hyoshik**; c/o MEMC Korea Company Ltd., 854, Manghynag-ro, Seonggeo-eup, Seobuk-gu, Cheonan-si, Chungcheongnam-do 31043 (KR). **LEE, Jaehoon**; c/o MEMC Korea Company Ltd., 854, Manghynag-ro, Seonggeo-eup, Seobuk-gu, Cheonan-si, Chungcheongnam-do 31043 (KR). **LEE, Byungchul**; c/o MEMC Korea Company Ltd., 854, Manghynag-ro, Seonggeo-eup, Seobuk-gu, Cheonan-si, Chungcheongnam-do 31043 (KR).

(72) Inventor *(for US only)*: **LEE, Minkyu**; c/o MEMC Korea Company Ltd., 854, Manghynag-ro, Seonggeo-eup, Seobuk-gu, Cheonan-si, Chungcheongnam-do 31043 (KR).

(74) Agent: **CHANG, Duck Soon** et al.; Kim & Chang, Seyang B/D, 39 Sajikno-8-gil, Jongno-gu, Seoul 03170 (KR).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI,

(54) Title: DOUBLE SIDE GRINDING APPARATUS HAVING CONVEX POLYGON-SHAPED ABRASIVE MEMBERS



(57) Abstract: Methods and apparatus for simultaneous double-side grinding semiconductor structures are disclosed. The double-side grinding apparatus may include first and second grinding wheels each having abrasive members that are shaped as a convex polygon (e.g., convex pentagon).

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WO 2022/231308 A1

NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) **Designated States** *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report (Art. 21(3))*